1. Disassembly Procedures

- S1 Turn off the monitor.
- S2 Place the monitor on a soft cloth or cushion

Press and hold the stand release button at the back of the display



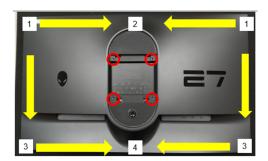
S3 Lift the stand assembly up and away from the monitor



S4 Unlock 4 screws on Rear Cover

Use hands or scraper bar to disassemble "Rear Cover" from monitor

Notice the disassembly order: Top Side=> Right / Left Side =>Bottom Side



(Screw Torque: 8-10 kgf)

S5 Unplug "FFC USB3 30/30" from USB BD

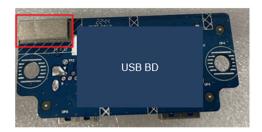
Unlock 2 screws on USB BD

Disassemble USB BD from Middle Frame



(Screw Torque: 4.5±0.5kgf)

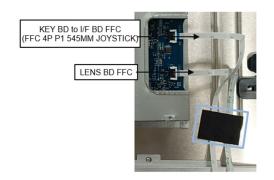
S6 Tear off a gasket from USB BD



S7 Tear off a tape from "LENS BD FFC" and "KEY BD to I/F BD FFC" on Panel

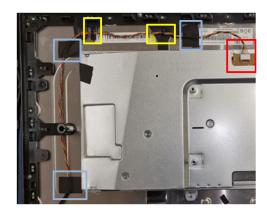
Unplug "LENS BD FFC" from I/F BD and tear off it from Panel

Unplug "KEY BD to I/F BD FFC" from I/F BD and tear off it from Panel



Tear off 3 tapes from the backlight wire on panel (See blue mark)

Unplug "Backlight Wire" from "LED DRV BD" (See red mark), then, disassemble it from the hooks on the upper left of Middle Frame (See yellow mark)



Unlock 2 screws to disassemble "Main SHD" from Panel



(Screw Torque: 4.5±0.5 kgf)

S10 Tear off a conductive cloth from "FFC EDP 51P/51P" on panel



S11 Tear off a yellow tape from "FFC EDP 51P/51P" on panel

Unplug "FFC EDP 51P/51P" from panel

Take off "Main SHD" from Panel



S12 Unlock 7 screws to disassemble Middle Frame and "ASSY BKT CHIN" (See blue marks)

Unlock 11 screws to disassemble Middle Frame and Panel (See red mark)

Disassemble Middle Frame from "ASSY BKT CHIN" and Panel

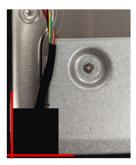


(Screw Torque-MF to Chin: 2.0±0.5 kgf) (Screw Torque-MF to panel: 2.0±0.5kgf)

S13 Disassemble "ASSY BKT CHIN" from panel

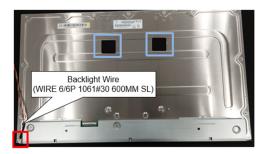


S14 Tear off an acetate tape from the connector of backlight on panel



S15 Tear off 2 acetate tapes from two convex hulls at the bottom of the panel

Unplug "Backlight Wire" from panel



S16 Tear off "LENS BD FFC" from Middle Frame

Unlock 2 screws to disassemble Power Button module from Middle Frame



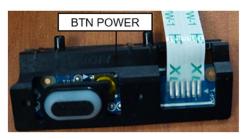
(Screw Torque: 1~1.1 kgf)

S17 Tear off "MYLAR PWR-KEY" from "LENS BD"



S18 Unlock 2 screws to disassemble "LENS BD" from "BTN POWER"





(Screw Torque: 1±0.05 kgf)

Unlock 2 screws to disassemble "HOLDER L" from Middle Frame

Take off "HOLDER L" from Middle Frame



(Screw Torque: 4~5 kgf)

S20 Unlock 2 screws to disassemble "Key BD" from "HOLDER L"

Take off "Key BD" from "HOLDER L"

Unplug "Key BD to I/F BD FFC" from "Key BD"



(Screw Torque: 1.8~2.0 kgf)

S21 Disassemble "MYLAR PWR" from Main SHD



S22 Unplug "FFC EDP 51P/51P" from I/F BD



S23 Tear off 2 acetate tapes from "SPS BD Wire" and "USB B BD to I/F BD wire" on Main SHD

Unlock 11 PCBA screws

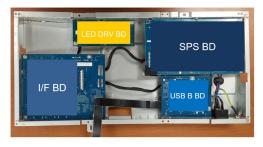


(Screw Torque: 8.5±1 kgf)

S24 Disassemble "USB B BD" from Main SHD and unplug "USB B BD to I/F BD wire" from "USB B BD"

Disassemble "LED DRV BD" from Main SHD and Uplug "LED DRV BD to I/F BD Wire" from "LED DRV BD"

Disassemble I/F BD from Main SHD and unplug "SPS BD Wire" from I/F BD

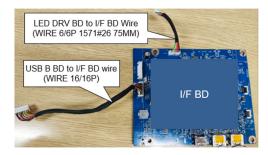




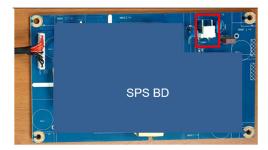
Unplug "FFC USB3 30/30" from "USB B **S25**



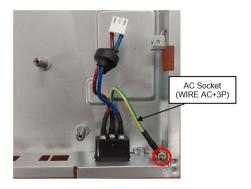
Unplug "LED DRV BD to I/F BD Wire" **S26** and "USB B BD to I/F BD wire" from I/F BD



Disassemble SPS BD from Main SHD **S27** and unplug "WIRE AC+3P" from SPS BD



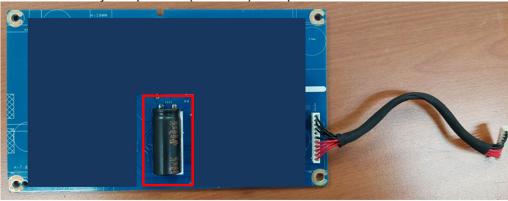
Unlock 1 ground screw and **S28** disassemble "WIRE AC+3P" from Main SHD



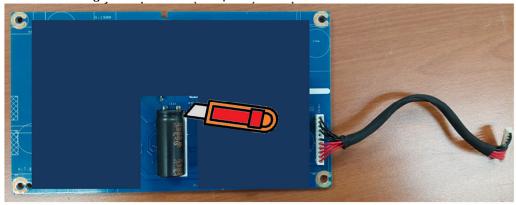
(Screw Torque: 8.5±1 kgf)

Remove electrolyte capacitors (red mark) from printed circuit boards

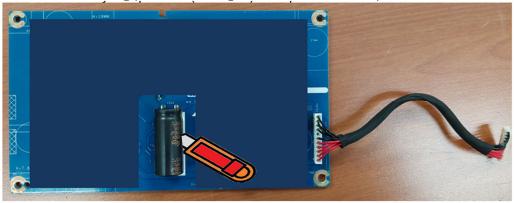
S29



S29-1 Cut the glue between bulk cap. and PCB with a knife



S29-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S29-3 Take out bulk cap. pin solder with soldering iron and absorber



S29-4 Lift the bulk cap. up and away from the PCB



2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater	Product has printed circuit boards
than 10 square cm)	(with a surface greater than 10 square
	cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and	No used
HC	
Gas discharge lamps	No used
LCD display > 100 cm2	Product has an LCD greater than 100
	cm2
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height	Product has electrolyte capacitors
> 25mm, diameter > 25mm)	(height >25mm, diameter > 25mm)

3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber